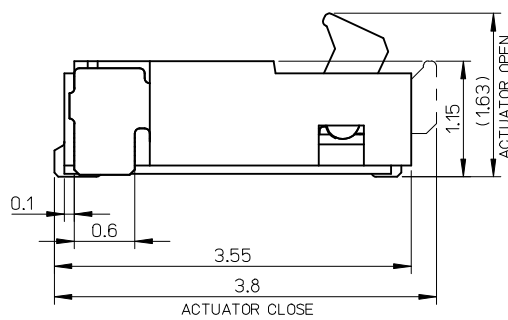
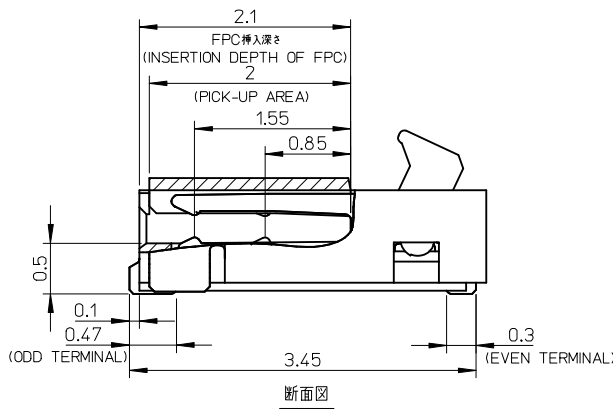
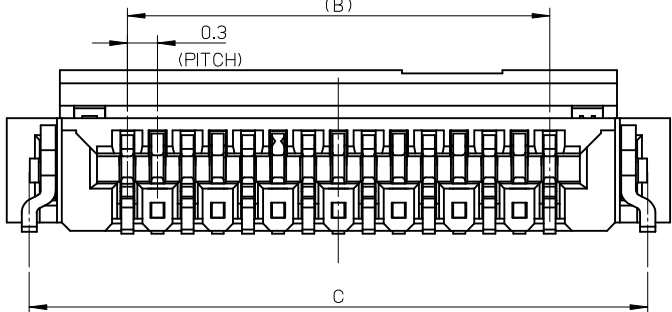
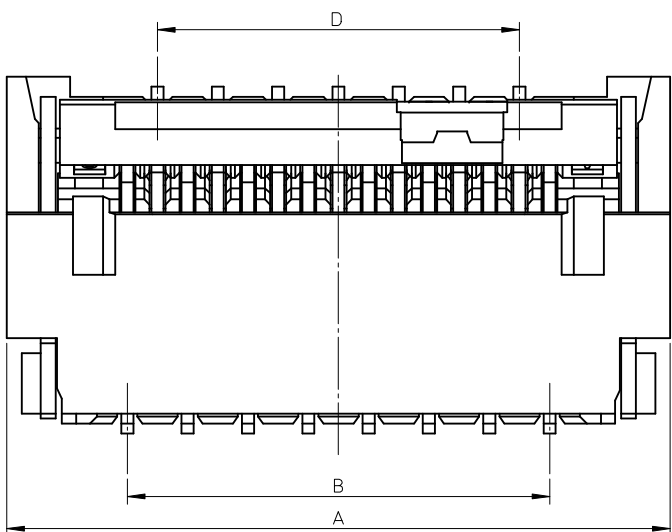


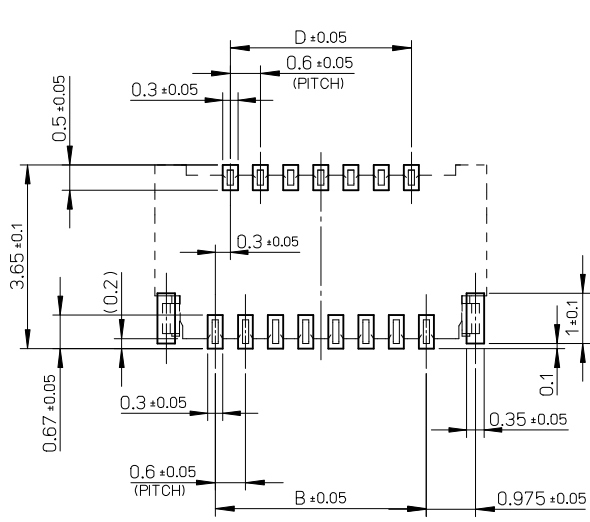
注記 NOTES:  
 1.材質 MATERIAL  
 ハウジング:LCP(液晶ポリマー)、白色、ガラス充填、UL94V-0  
 HOUSING:LIQUID CRYSTAL POLYMER,WHITE(NATURAL)  
 GLASS FILLED,UL94V-0  
 アクチュエータ:ポリアミド樹脂  
 黒色、ガラス充填、UL94HB  
 ACTUATOR: POLYAMIDE  
 BLACK GLASS FILLED,UL94HB  
 ターミナル:燐青銅 (t=0.12)  
 TERMINAL:PHOSPHOR BRONZE(t=0.12)  
 金具:燐青銅(t=0.15)  
 NAIL:PHOSPHOR BRONZE(t=0.15)  
 2.めっき仕様 PLATING  
 ターミナル TERMINAL  
 接点部:金めっき 0.1μm以上  
 CONTACT AREA: GOLD 0.1 MICROMETER MINIMUM  
 半田付け部:金めっき  
 SOLDER TAIL AREA: GOLD  
 下地めっき:ニッケル 1.0μm以上  
 UNDER PLATING:NICKEL 1.0 MICROMETER MINIMUM  
 金具 NAIL  
 錫めっき 1.0μm以上  
 TIN PLATING 1.0 MICROMETER MINIMUM  
 下地めっき:ニッケル 1.0μm以上  
 UNDER PLATING:NICKEL 1.0 MICROMETER MINIMUM  
 3.平坦度は、0.1ミリ以下とする。  
 TAILS COPLANARITY TO BE 0.1 MAXIMUM.  
 4.ELV及びRoHS適合品  
 ELV AND RoHS COMPLIANT  
 5.本製品は502598-\*\*91の端子材料変更品である。  
 THIS PRODUCT IS CHANGE OF TERMINAL MATERIAL FOR 502598-\*\*91.



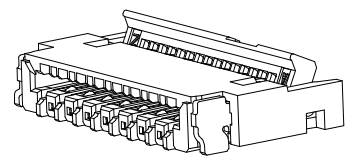
0.125	14.4	16.95	15	17.4	502598-5193	51
0.112	12.6	15.15	13.2	15.6	502598-4593	45
0.105	11.4	13.95	12.0	14.4	502598-4193	41
0.098	10.8	13.35	11.4	13.8	502598-3993	39
0.085	9	11.55	9.6	12	502598-3393	33
0.077	7.8	10.35	8.4	10.8	502598-2993	29
0.072	7.2	9.75	7.8	10.2	502598-2793	27
0.068	6.6	9.15	7.2	9.6	502598-2593	25
0.063	6	8.55	6.6	9	502598-2393	23
0.048	4.2	6.75	4.8	7.2	502598-1793	17
0.043	3.6	6.15	4.2	6.6	502598-1593	15
重さ (g) WEIGHT(g)	D	C	B	A	EMBOSSED PACKAGE オーダー番号 ORDER NO.	極数 CIRCUITS

CONNECTOR SERIES NO. 502598-\*\*21

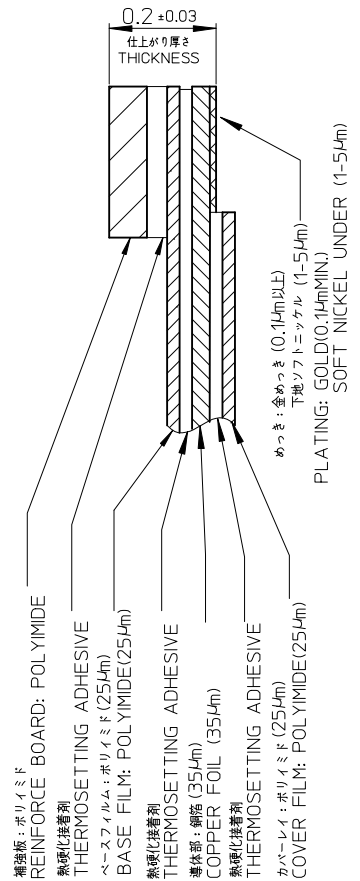
REVISED IEC NO: J2014-0146 DRW: NIKAGUMO 2013/07/25 CHK: D: TAKAHASHI 2013/08/30 APPR: YNOGAWA 2013/08/28	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION 0.3 FPC CONN. BACK FLIP HOUSING ASSY <b>molex</b> DOCUMENT NO. SD-502598-003 SHEET NO. 1 OF 2
	10 UNDER ±0.2		MM ONLY	---	METRIC	
	10 OVER 30 UNDER ±0.25		DRAWN BY DATE	TITLE		
	30 OVER ±0.3		KMIYAHARA 2012/07/18	0.3 FPC CONN. BACK FLIP HOUSING ASSY		
B REV	ANGULAR ±1 °		CHECKED BY DATE	MATERIAL NO.		
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		KTAKAHASHI 2012/07/18	SEE TABLE		
			APPROVED BY DATE	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		
			KMORIKAWA 2012/08/01			



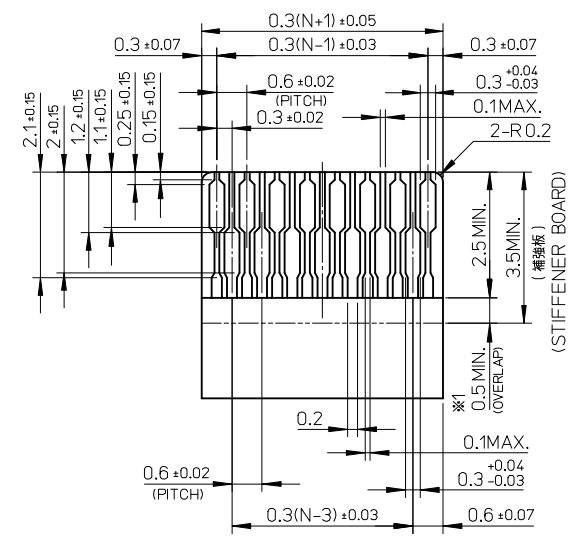
推奨基板寸法  
 RECOMMENDED P.W.B. PATTERN LAYOUT  
 マスク厚: 100 μm  
 マスク開口率: 100%  
 SCREEN THICKNESS: 100 μm  
 SCREEN OPEN RATIO: 100%



ISO VIEW (参考)



FPC構成推奨仕様  
 STRUCTURE OF FPC



適合する金めっきFPC推奨寸法  
 APPLICABLE FPC OF GOLD PATING  
 RECOMMENDED DIMENSION

(仕上がり厚さ: 0.2 ± 0.03)  
 (THICKNESS: 0.2 ± 0.03)

FPCについて:  
 抜き方向は、導体側から補強板側を推奨致します。  
 補強フィルム材質は、ポリイミドを推奨致します。  
 接着剤は熱硬化接着剤を推奨致します。  
 尚、接着剤の接点部への付着は導通不良の原因になりますので、  
 染み出しが無い様、お願い致します。

ABOUT FPC:  
 RECOMMENDED PUNCHER DIRECTION:  
 FROM CONDUCTOR SIDE TO STIFFNER FILM SIDE.  
 RECOMMENDED MATERIAL:  
 STIFFENER FILM: POLYIMIDE  
 BONDING AGENT: THERMOSETTING AGENT  
 PLEASE PUT APPROPRIATE AMOUNT OF ADHESIVE ON  
 ADHEREND BECAUSE THERE IS A POSSIBILITY THAT  
 THE EXTRA ADHESIVE CAUSES THE DEFECT IN  
 ELECTRICAL CONTINUITY.

N: 極数  
 N: CIRCUITS

REVISED EC NO: J2014-0146 DRWN: KIKAGURO 2013/07/25 CHKD: KAKAHASHI 2013/08/30 APPR: YNOGAWA 2013/08/28	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
	10 UNDER	± 0.2	DRAWN BY KMIYAHARA	DATE 2012/07/18	TITLE 0.3 FPC CONN. BACK FLIP HOUSING ASSY				
	10 OVER 30 UNDER	± 0.25	CHECKED BY KTAKAHASHI	DATE 2012/07/18	molex DOCUMENT NO. SD-502598-003 SHEET NO. 2 OF 2				
	30 OVER	± 0.3	APPROVED BY KMORIKAWA	DATE 2012/08/01					
REV	DESCRIPTION	ANGULAR ±1 °	MATERIAL NO. SEE TABLE		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3					